General Purpose Transistors

PNP Silicon

Features

- S Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC–Q101 Qualified and PPAP Capable
- These Devices are Pb–Free, Halogen Free/BFR Free and are RoHS Compliant

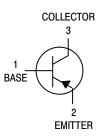


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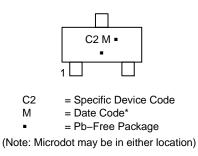
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SOT-23 (TO-236) CASE 318-08 STYLE 6



MARKING DIAGRAM



*Date Code orientation and/or overbar may vary depending upon manufacturing location.

ORDERING INFORMATION

Device	Package	Shipping
BCW30LT1G	SOT-23 (Pb-Free)	3,000/Tape & Reel
SBCW30LT1G	SOT-23 (Pb-Free)	3,000/Tape & Reel

+For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Collector – Emitter Voltage	V _{CEO}	-32	Vdc
Collector – Base Voltage	V _{CBO}	-32	Vdc
Emitter-Base Voltage	V _{EBO}	-5.0	Vdc
Collector Current – Continuous	Ι _C	-100	mAdc

THERMAL CHARACTERISTICS

Characteristic	Symbol	Value	Unit
Total Device Dissipation FR-5 Board (Note 1) $T_A = 25^{\circ}C$	P _D	225	mW
Derate above 25°C		1.8	mW/°C
Thermal Resistance, Junction–to–Ambient	R_{\thetaJA}	556	°C/W
Total Device Dissipation Alumina Substrate (Note 2) $T_A = 25^{\circ}C$	P _D	300	mW
Derate above 25°C		2.4	mW/°C
Thermal Resistance, Junction–to–Ambient	R_{\thetaJA}	417	°C/W
Junction and Storage Temperature	T _J , T _{stg}	-55 to +150	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

1. FR-5 = $1.0 \times 0.75 \times 0.062$ in.

2. Alumina = $0.4 \times 0.3 \times 0.024$ in. 99.5% alumina.



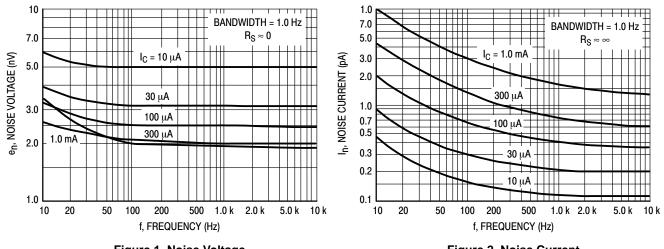
ELECTRICAL CHARACTERISTICS ($T_A = 25^{\circ}C$ unless otherwise noted)

Characteristic	Symbol	Min	Max	Unit
OFF CHARACTERISTICS				
Collector–Emitter Breakdown Voltage ($I_C = -2.0 \text{ mAdc}, I_E = 0$)	V _{(BR)CEO}	-32	_	Vdc
Collector–Emitter Breakdown Voltage ($I_C = -100 \ \mu Adc, \ V_{EB} = 0$)	V _{(BR)CES}	-32	_	Vdc
Collector–Base Breakdown Voltage $(I_C = -10 \ \mu Adc, I_C = 0)$	V _{(BR)CBO}	-32	_	Vdc
Emitter–Base Breakdown Voltage $(I_E = -10 \ \mu Adc, I_C = 0)$	V _{(BR)EBO}	-5.0	_	Vdc
Collector Cutoff Current $(V_{CB} = -32 \text{ Vdc}, I_E = 0)$ $(V_{CB} = -32 \text{ Vdc}, I_E = 0, T_A = 100^{\circ}\text{C})$	І _{СВО}	-	-100 -10	nAdc μAdc
ON CHARACTERISTICS	<u> </u>			
DC Current Gain (I _C = -2.0 mAdc, V _{CE} = -5.0 Vdc)	h _{FE}	215	500	_
Collector–Emitter Saturation Voltage ($I_C = -10 \text{ mAdc}, I_B = -0.5 \text{ mAdc}$)	V _{CE(sat)}	-	-0.3	Vdc
Base-Emitter On Voltage ($I_C = -2.0 \text{ mAdc}, V_{CE} = -5.0 \text{ Vdc}$)	V _{BE(on)}	-0.6	-0.75	Vdc
MALL-SIGNAL CHARACTERISTICS				•
Output Capacitance ($I_E = 0$, $V_{CB} = -10$ Vdc, f = 1.0 MHz)	C _{obo}	_	7.0	pF
Noise Figure (I _C = -0.2 mAdc, V _{CE} = -5.0 Vdc, R _S = 2.0 k Ω , f = 1.0 kHz, BW = 200 Hz)	NF	_	10	dB

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

TYPICAL NOISE CHARACTERISTICS

 $(V_{CE} = -5.0 \text{ Vdc}, T_A = 25^{\circ}C)$



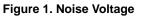


Figure 2. Noise Current

NOISE FIGURE CONTOURS

 $(V_{CE}=-5.0~Vdc,~T_{A}=25^{\circ}C)$

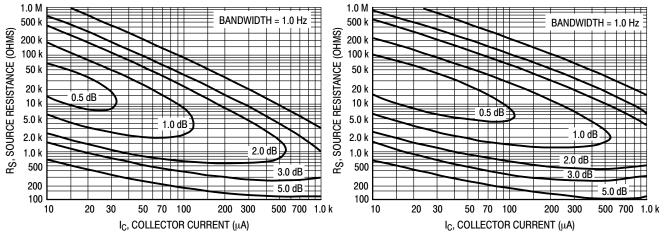


Figure 3. Narrow Band, 100 Hz



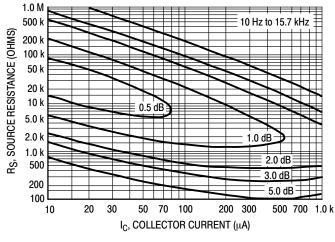


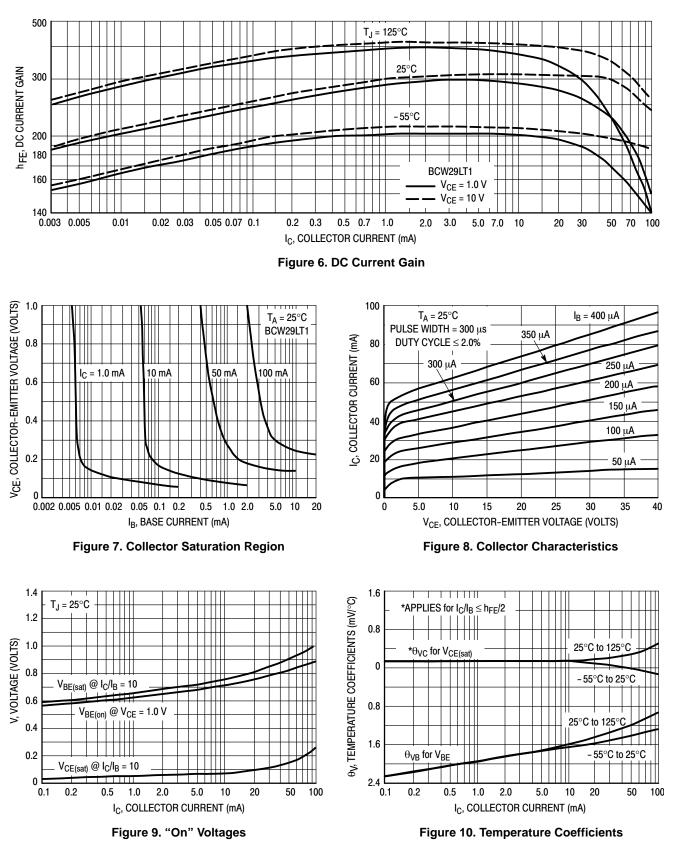
Figure 5. Wideband

Noise Figure is Defined as:

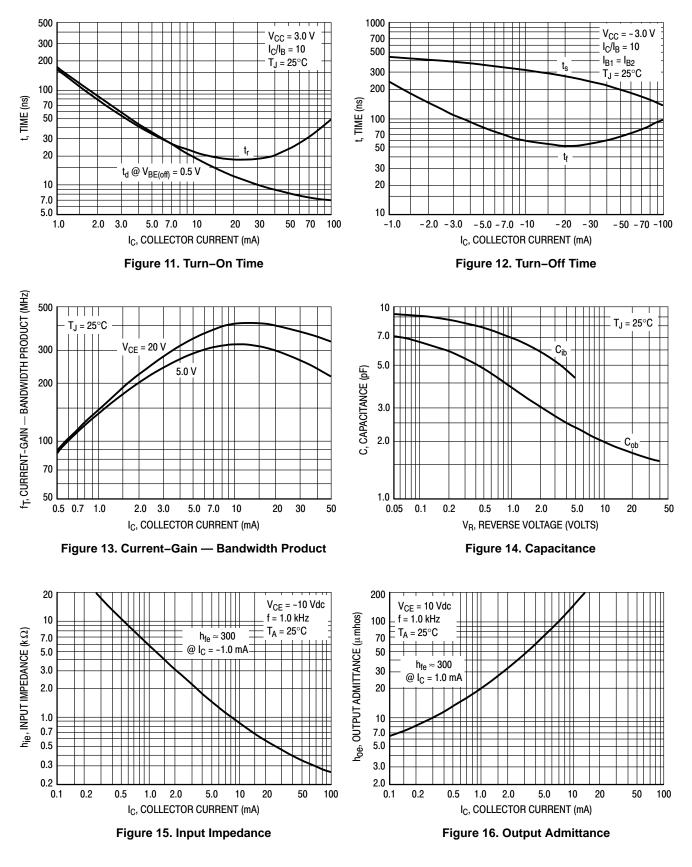
$$NF = 20 \log_{10} \left[\frac{e_{n}^{2} + 4KTR_{S} + I_{n}^{2}R_{S}^{2}}{4KTR_{S}} \right]^{1/2}$$

- e_n = Noise Voltage of the Transistor referred to the input. (Figure 3)
- I_n = Noise Current of the Transistor referred to the input. (Figure 4)
- \ddot{K} = Boltzman's Constant (1.38 x 10⁻²³ j/°K)
- T = Temperature of the Source Resistance ($^{\circ}$ K)
- R_S = Source Resistance (Ohms)

TYPICAL STATIC CHARACTERISTICS



TYPICAL DYNAMIC CHARACTERISTICS



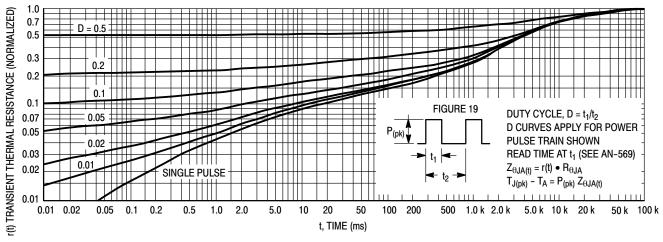


Figure 17. Thermal Response

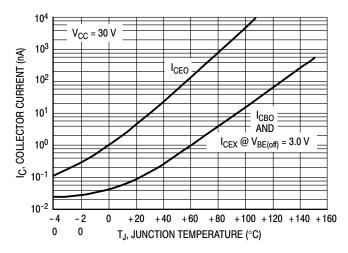


Figure 18. Typical Collector Leakage Current

DESIGN NOTE: USE OF THERMAL RESPONSE DATA

A train of periodical power pulses can be represented by the model as shown in Figure 19. Using the model and the device thermal response the normalized effective transient thermal resistance of Figure 17 was calculated for various duty cycles.

To find $Z_{\theta JA(t)},$ multiply the value obtained from Figure 17 by the steady state value $R_{\theta JA}.$

Example:

The BCW29LT1 is dissipating 2.0 watts peak under the following conditions:

Using Figure 17 at a pulse width of 1.0 ms and D = 0.2, the reading of r(t) is 0.22.

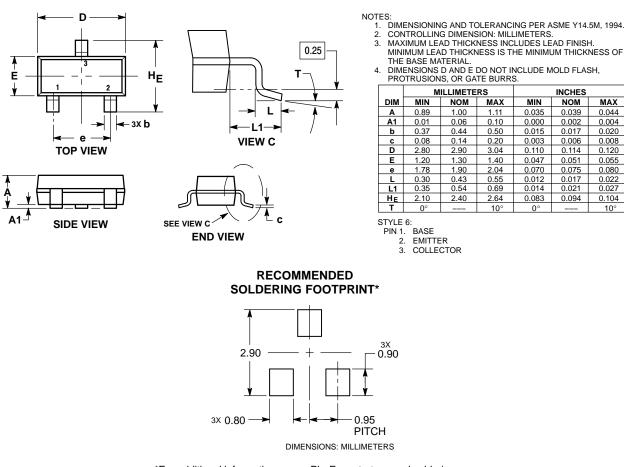
The peak rise in junction temperature is therefore

 $\Delta T = r(t) \times P_{(pk)} \times R_{\theta JA} = 0.22 \times 2.0 \times 200 = 88^{\circ}C.$

For more information, see AN–569.

PACKAGE DIMENSIONS

SOT-23 (TO-236) CASE 318-08 ISSUE AR



*For additional information on our Pb–Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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